

# Description

The 25N50 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

# TO-3P

#### **General Features**

 $V_{DS} = 500V, I_{D} = 25A$ 

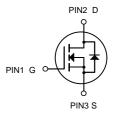
 $R_{DS(ON)}$  < 240m  $\Omega$  @  $V_{GS}$ =10V

# **Application**

High efficiency switch mode power supplies

Power factor correction

Electronic lamp ballast



N-Channel MOSFET

# **Package Marking and Ordering Information**

Product ID	Pack	Marking	Units Tube
25N50	TO-3P	HXY 25N50 YYYY	50

# Absolute Maximum Ratings@T<sub>j</sub>=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	500	V
VGS	Gate-Source Voltage	<u>+</u> 20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Drain Current	25	Α
IDM	Pulsed Drain Current <sup>1</sup>	100	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	300	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C



# Electrical Characteristics (T<sub>C</sub>=25 <sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·		•			
Drain-Source Breakdown Voltage (Note 1)	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	500	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics	·		•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.0	-	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =14A	-	200	240	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =40V,I <sub>D</sub> =10A	-	25	-	S
Dynamic Characteristics	·		•			
Input Capacitance	C <sub>lss</sub>	)/ O5)/)/ O)/	-	3500	-	PF
Output Capacitance	Coss	$V_{DS}$ =25V, $V_{GS}$ =0V, F=1.0MHz	-	220	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	r-1.0ivinz	-	12	-	PF
Switching Characteristics	·		•			
Turn-on Delay Time	t <sub>d(on)</sub>		-	40	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =400 $V$ , $I_{D}$ =25 $A$	-	68	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=10 \Omega^{(Note 2)}$	-	88	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	44	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =400V,I <sub>D</sub> =25A, V <sub>GS</sub> =10V <sup>(Note 2)</sup>	-	65	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	12	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	v <sub>GS</sub> -10v	-	20	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =14A	-		1.4	V
Diode Forward Current (Note 2)	Is		-	-	25	Α

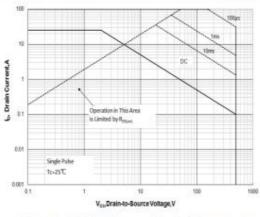
#### Notes:

<sup>1.</sup> Repetitive Rating: Pulse width limited by maximum junction temperature.

**<sup>2.</sup>** Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2\%$ .



# **Typical Electrical**



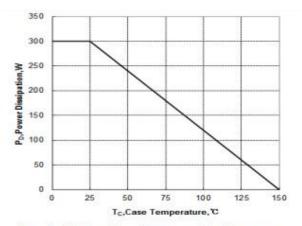
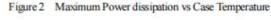
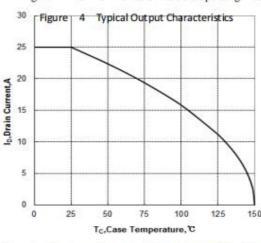


Figure 1 Maximum Forward Bias Safe Operating Area





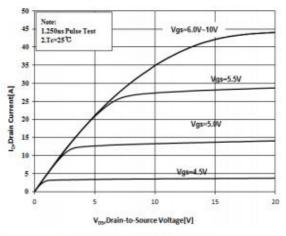


Figure 3 Maximum Continuous Drain Current vs Case Temperature

Figure 4 Typical Output Characteristics

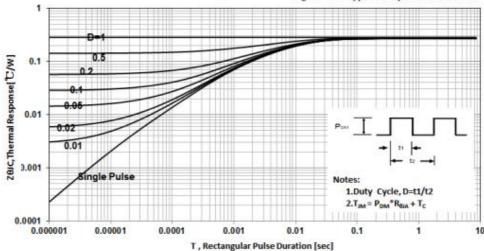


Figure 5 Maximum Effective Thermal Impedance, Junction to Case

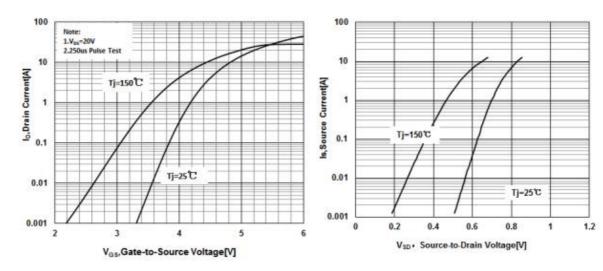


Figure 6 Typical Transfer Characteristics

Figure 7 Typical Body Diode Transfer Characteristics

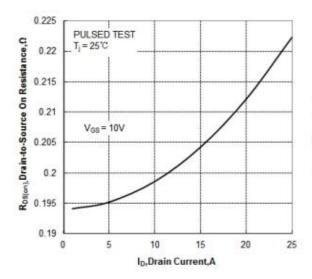


Figure 8 Typical Drain to Source ON Resistance vs Drain Current

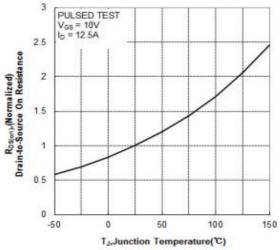


Figure 9 Typical Drian to Source on Resistance vs Junction Temperature

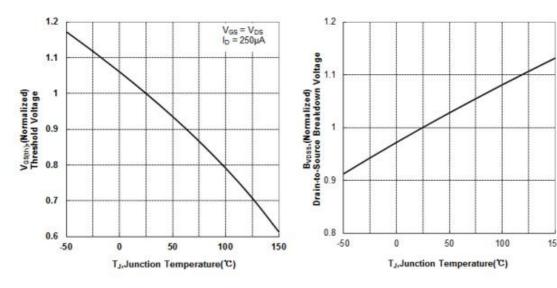


Figure 10 Typical Theshold Voltage vs Junction Temperature

Figure 11 Typical Breakdown Voltage vs Junction Temperature

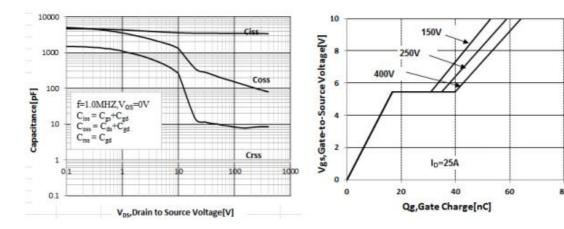
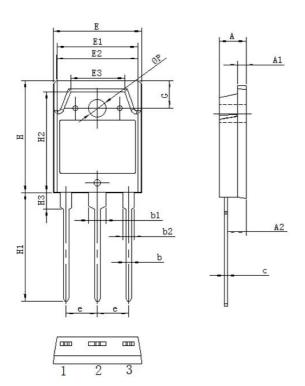


Figure 12 Typical Capacitance vs Drain to Source Voltage

Figure 13 Typical Gate Charge vs Gate to Source Voltage



# Package Information TO-3P



Symbol	单位 mm			
	Min	Nom	Max	
A	4.60	4. 80	5. 00	
A1	1. 3	1. 5	1. 7	
A2	1. 20	1. 40	1. 60	
b	0.80	1. 0	1. 20	
b1	2. 90	3. 10	3. 30	
b2	1. 90	2. 10	2. 30	
С	0. 50	0.60	0.70	
е	5. 25	5. 45	5. 65	
E	15. 2	15. 6	16. 0	
E1	13. 2	13. 4	13. 6	
E2	13. 1	13. 3	13. 5	
E3	9. 1	9. 3	9. 5	
Н	19.8	20.0	20. 2	
H1	20. 1	20. 3	20. 5	
H2	18. 5	18. 7	18. 9	
НЗ	3. 2	3. 5	3.8	
G	4.8	5. 0	5. 2	
ФР	3.00	3. 20	3. 40	



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